

ABSTRACT

A jig structure for an integrated circuit package. The jig structure is used for integrated circuits to be covered by glue. The jig structure includes a base formed with a plurality of receiving regions for receiving the integrated circuits, a mold plate covering the base, a plurality of glue inlets formed on the mold plate at locations corresponding to each receiving region on the base, and a projection arranged between each glue inlet and its corresponding receiving region. The projection blocks and buffers the glue entering the receiving regions from the glue inlets. According to the jig structure, the mold flow of the glue can be effectively buffered when the glue is poured. Thus, it is not necessary to redesign the jig with the change of the relative position relationships between the glue inlets and the integrated circuits. The jig of this invention can be widely used for packaging various integrated circuits having different sizes and specifications.